

FIG.1

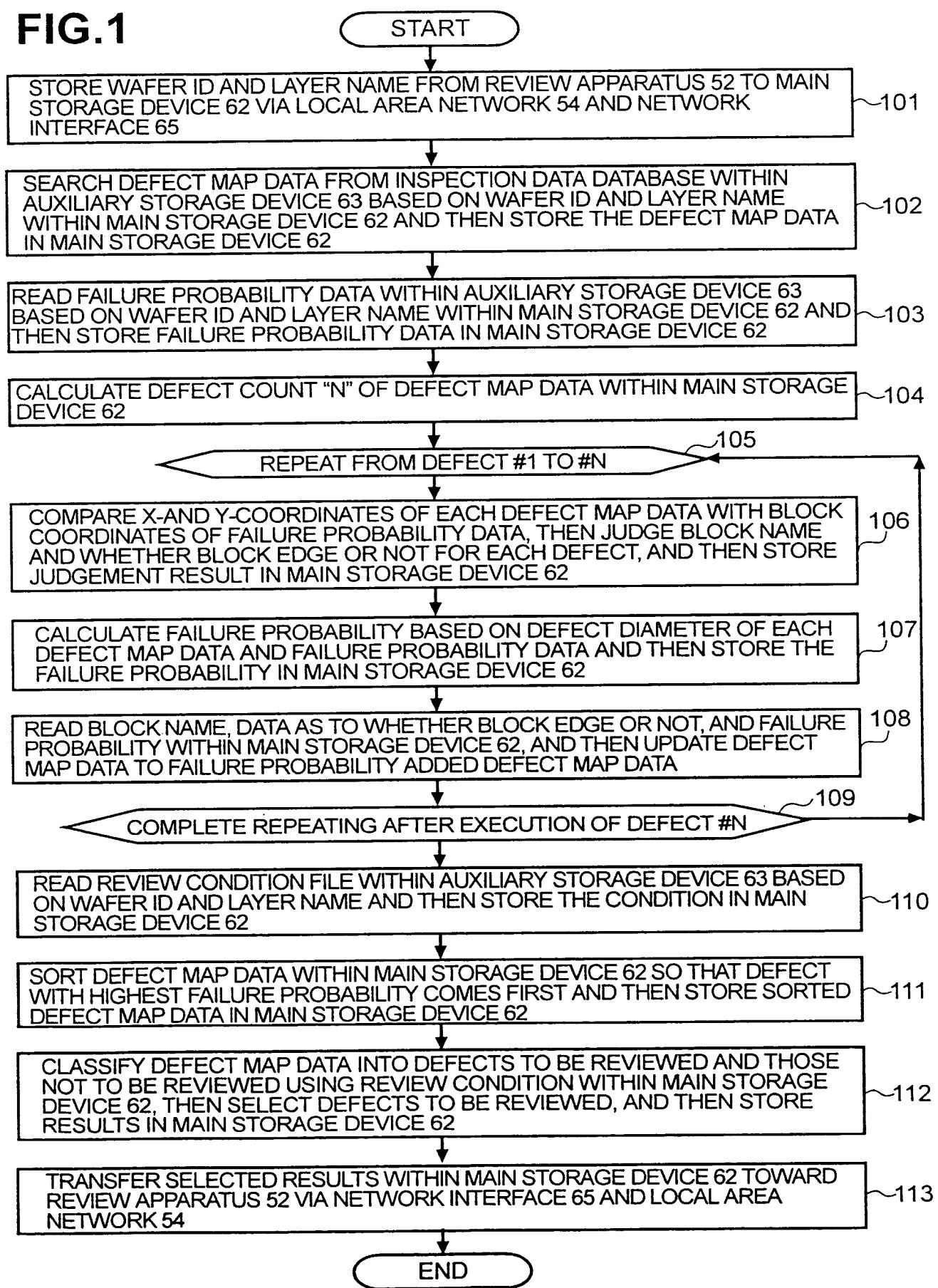


FIG.2

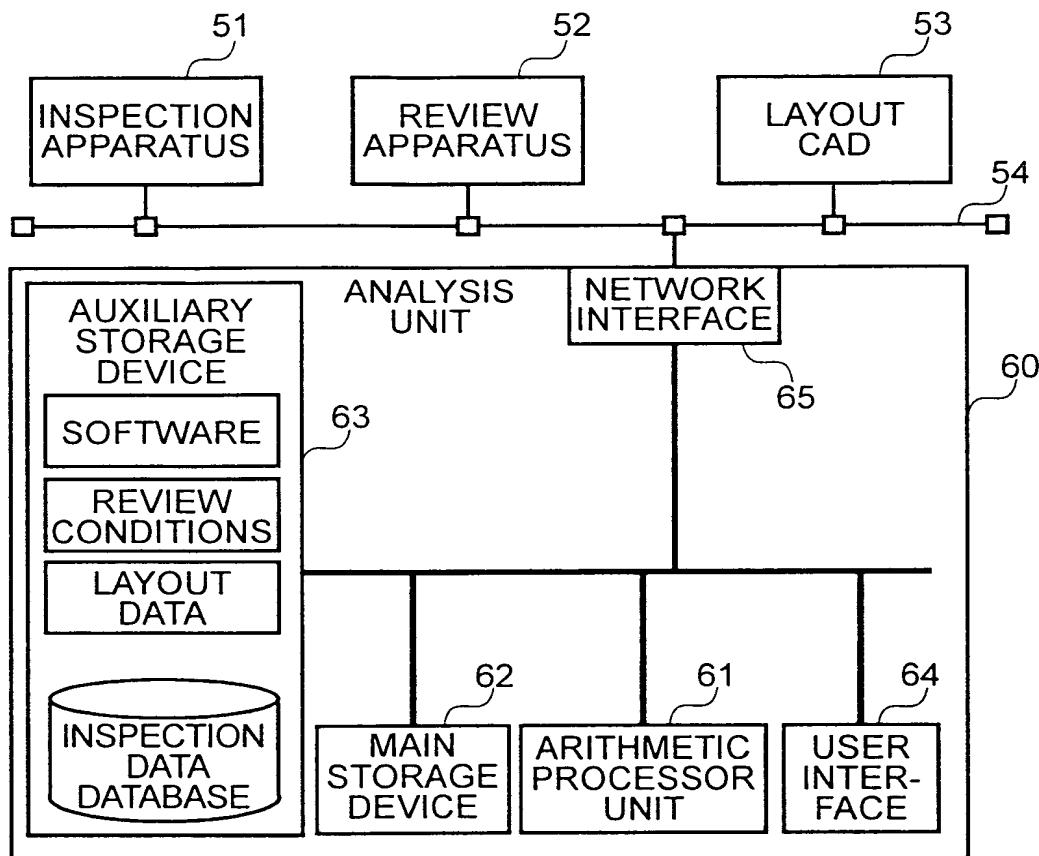


FIG.3

CHIP NO.,	COLUMN,	ROW,	X,	Y,	DEFECT DIAMETER
1,	1,	1,	73,	67,	2.4
2,	5,	1,	25,	89,	0.3
3,	4,	2,	47,	69,	1.5
4,	5,	3,	80,	82,	1.0
5,	6,	5,	52,	78,	1.2
6,	3,	5,	71,	32,	0.2
7,	3,	7,	87,	90,	0.7
8,	2,	6,	77,	38,	0.3
9,	0,	4,	83,	45,	0.8
10,	2,	3,	49,	9,	1.9

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FIG.4

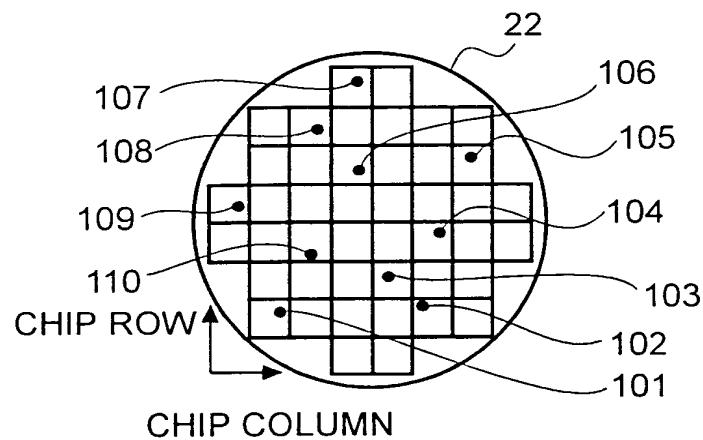
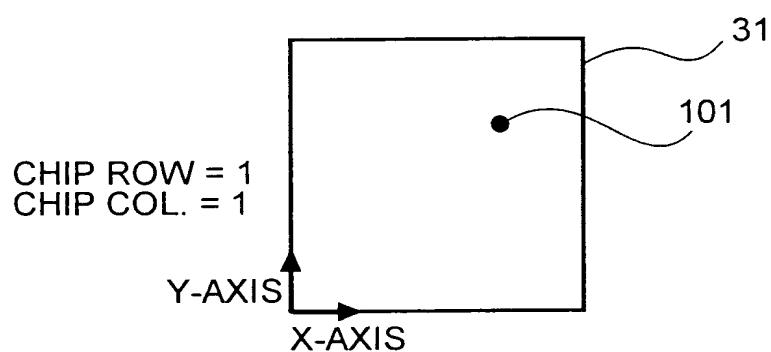


FIG.5



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FIG.6

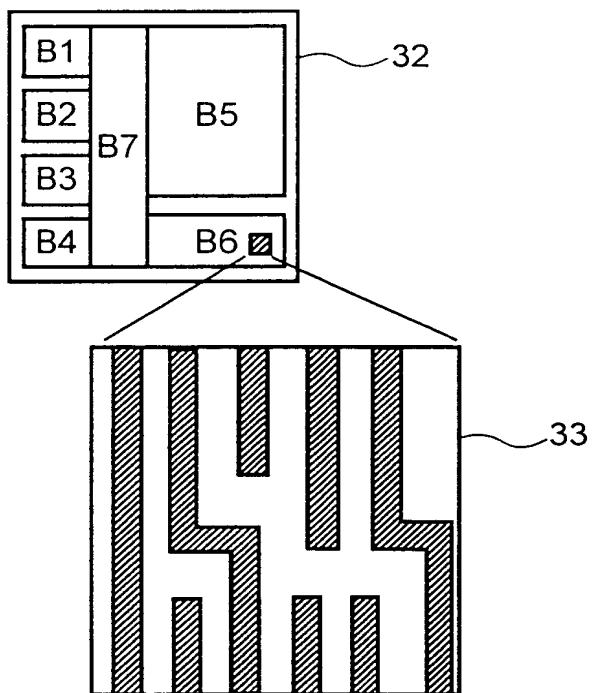


FIG.7

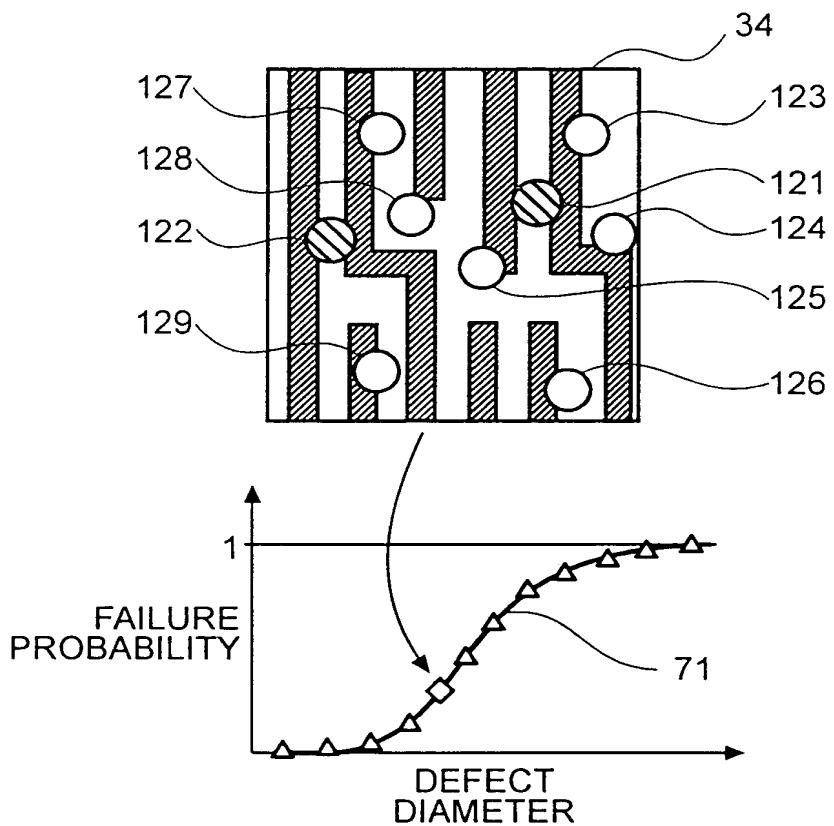


FIG.8

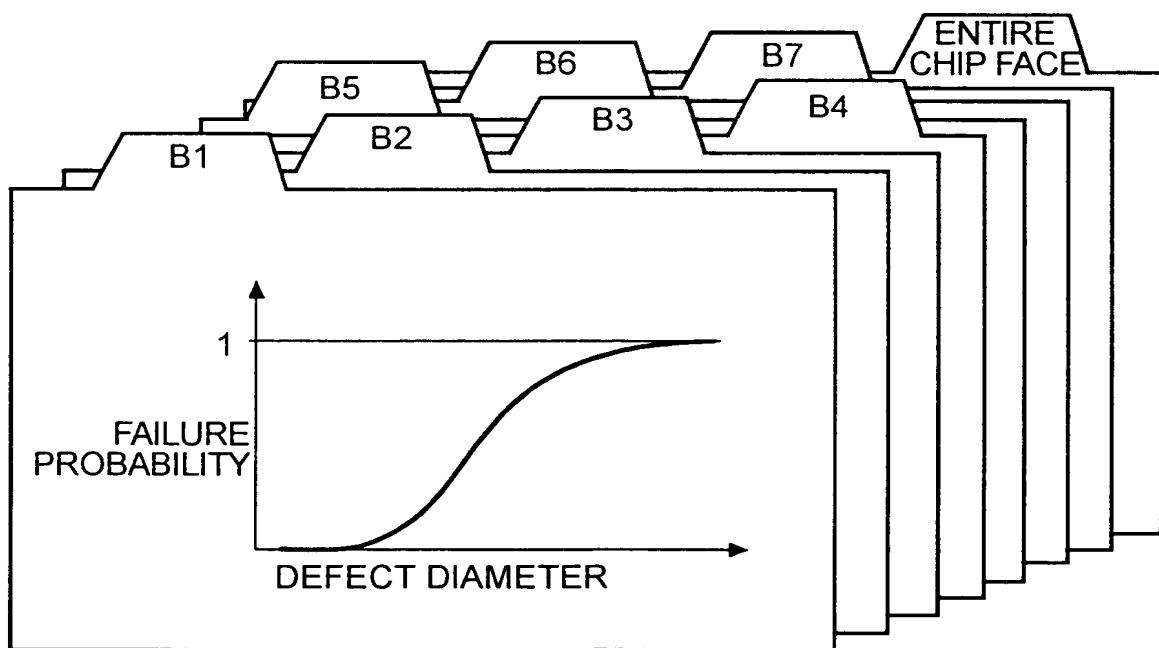


FIG.9

PRODUCT TYPE NAME	LOGIC234	72
LAYER NAME	METAL1	
BLOCK NAME	B1	
BLOCK COORDINATES	RECTANGLE DIAGONAL	
	ANGLE (5, 80) - (20, 95)	
DEFECT	FAILURE	
DIAMETER	PROBABILITY	
0.05,	0.00	
0.10,	0.01	
0.15,	0.02	
0.20,	0.03	
0.25,	0.05	
.	.	
.	.	
9.95,	1.00	
10.00,	1.00	

FIG.10

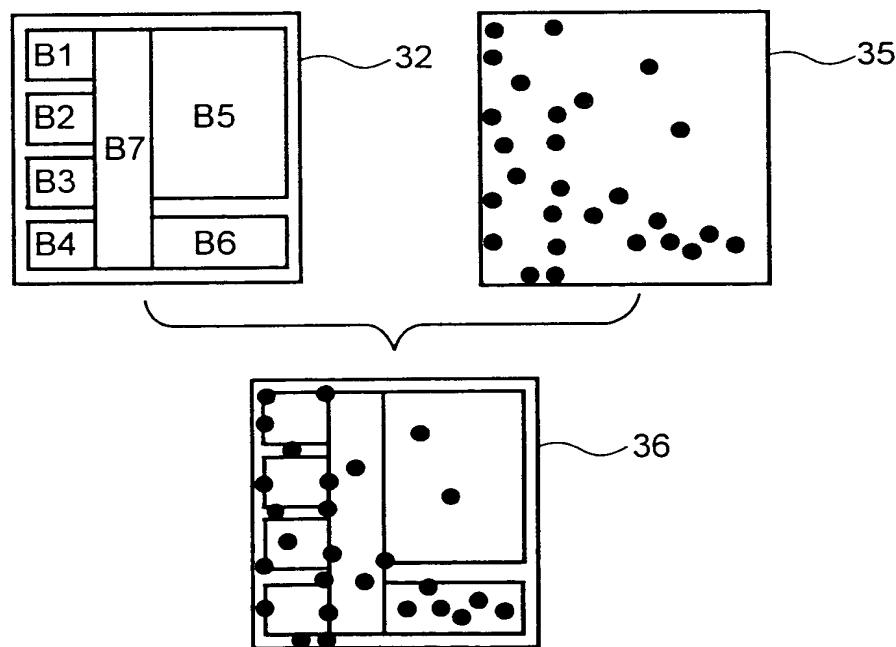


FIG.11

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NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06

FIG.12

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NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05

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FIG.13

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NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26

FIG.14

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NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
3,	4,	2,	47,	69,	1.5,	B2,	no,	0.26
8,	2,	6,	77,	38,	0.3,	B6,	no,	0.07
2,	5,	1,	25,	89,	0.3,	B1,	no,	0.07
10,	2,	3,	49,	9,	1.9,	B7,	no,	0.06
6,	3,	5,	71,	32,	0.2,	B6,	yes,	0.05

FIG.15

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NO.,	CHIP COL.,	CHIP ROW,	X,	Y,	SIZE,	BLOCK,	BLOCK EDGE,	FAILURE PROBABILITY
1,	1,	1,	73,	67,	2.4,	B5,	no,	0.83
5,	6,	5,	52,	78,	1.2,	B5,	yes,	0.50
4,	5,	3,	80,	82,	1.0,	B5,	no,	0.38
7,	3,	7,	87,	90,	0.7,	B5,	no,	0.35
9,	0,	4,	83,	45,	0.8,	B5,	no,	0.28

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FIG.16

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PRODUCT TYPE NAME
LOGIC234
LAYER NAME
METAL1
MAXIMUM DEFECT NUMBER
20
OBJECT
FAILURE PROBABILITY
0.30 OR GREATER
EXCLUDED
B5
BLOCK EDGES B1, B2

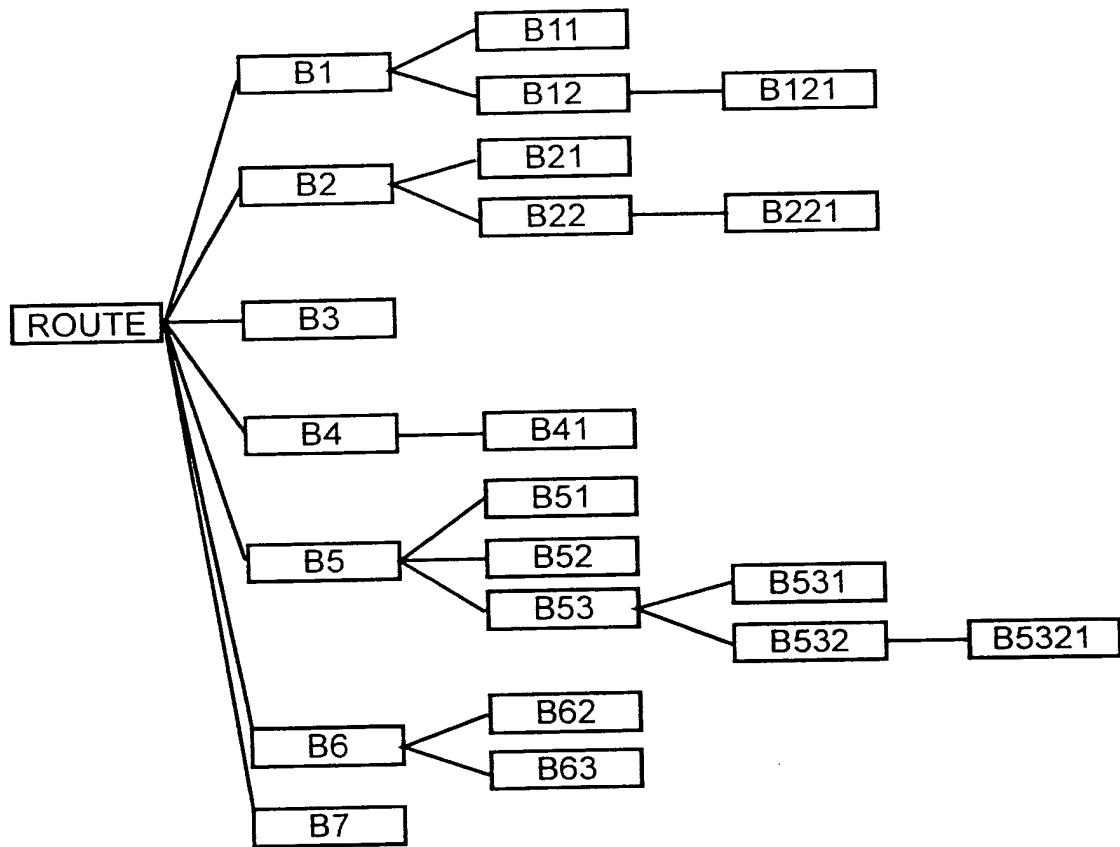
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FIG.17

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FIG.18

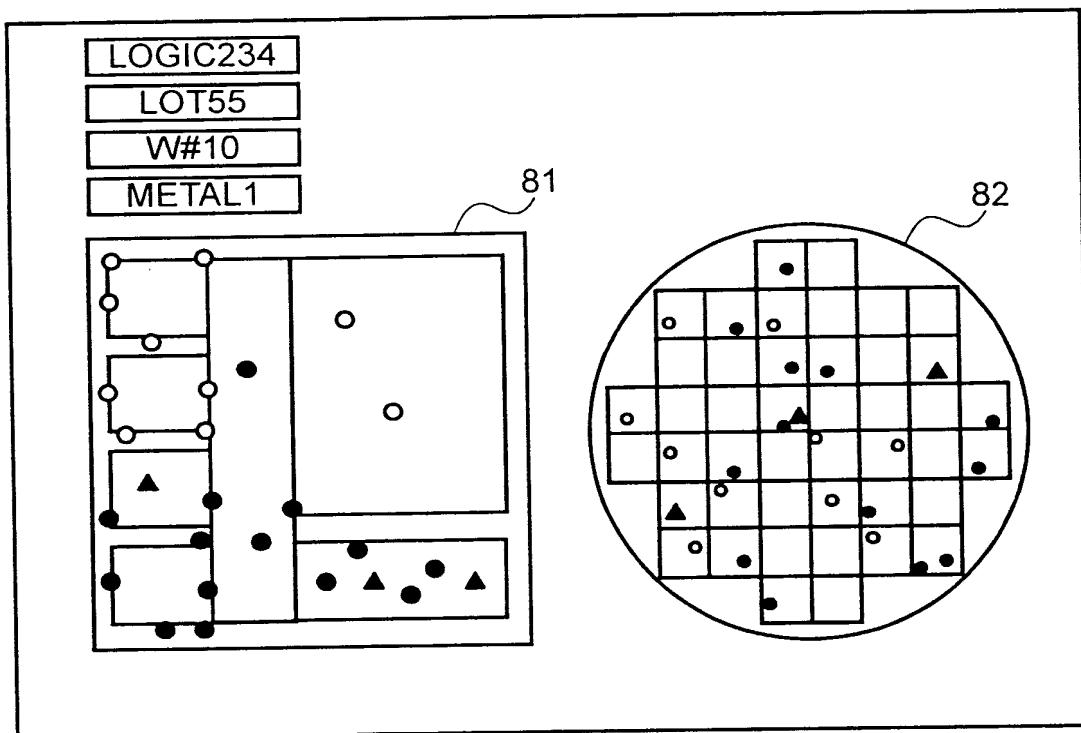


FIG.19

